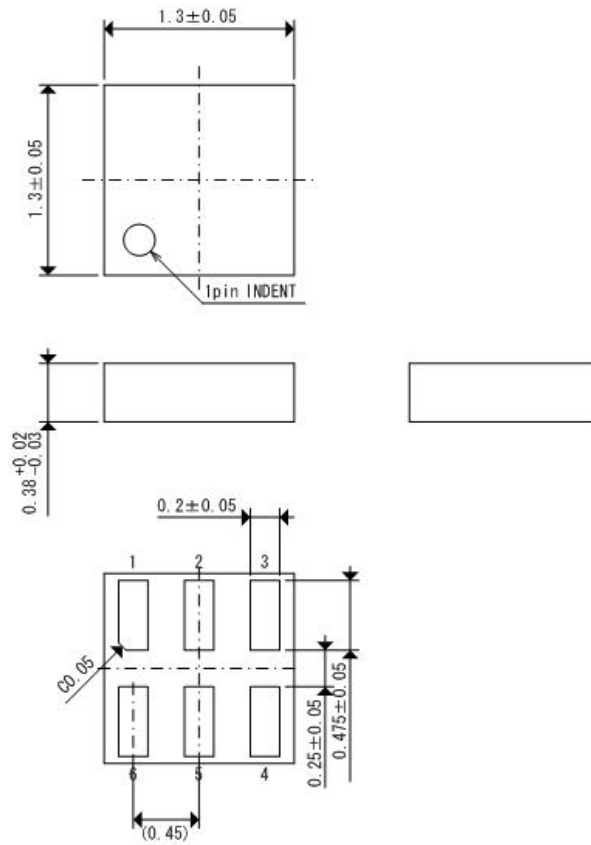


Packaging Information / Reference Pattern Layout Dimensions

●USPN-6

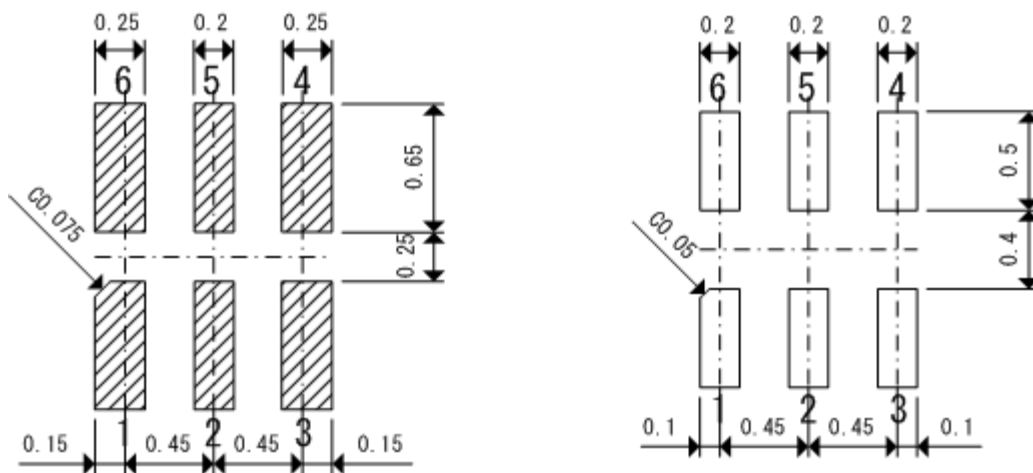
Unit: mm

■Packaging Information



■Reference Pattern Layout Dimension

Note : reference metal mask design





**●USPN-6 Power Dissipation**

Power dissipation data for the USPN-6 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

**1. Measurement Condition (Reference data)**

Condition : Mount on a board

Ambient : Natural convection

Soldering : Lead (Pb) free

Board : Dimensions 40mm x 40 mm (1600mm<sup>2</sup>)

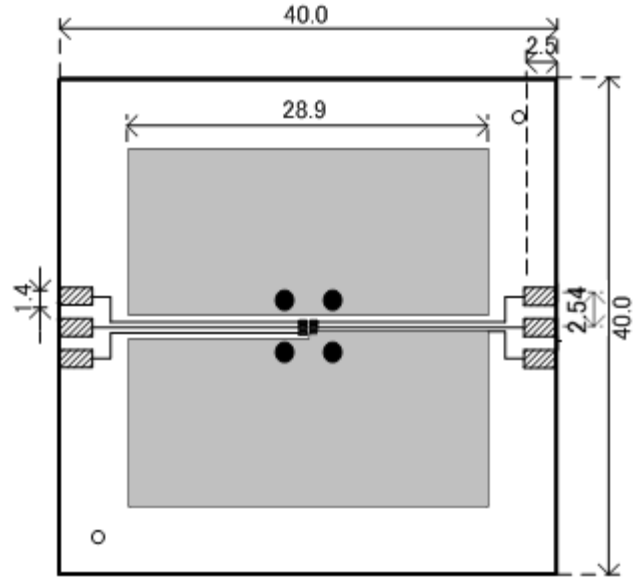
Copper (Cu) traces occupy 50% of the front and 50% of the back.

VSS pin is tied to the copper traces

Material : Glass Epoxy (FR-4)

Thickness : 1.6mm

Through-hole : 4 x 0.8 Diameter

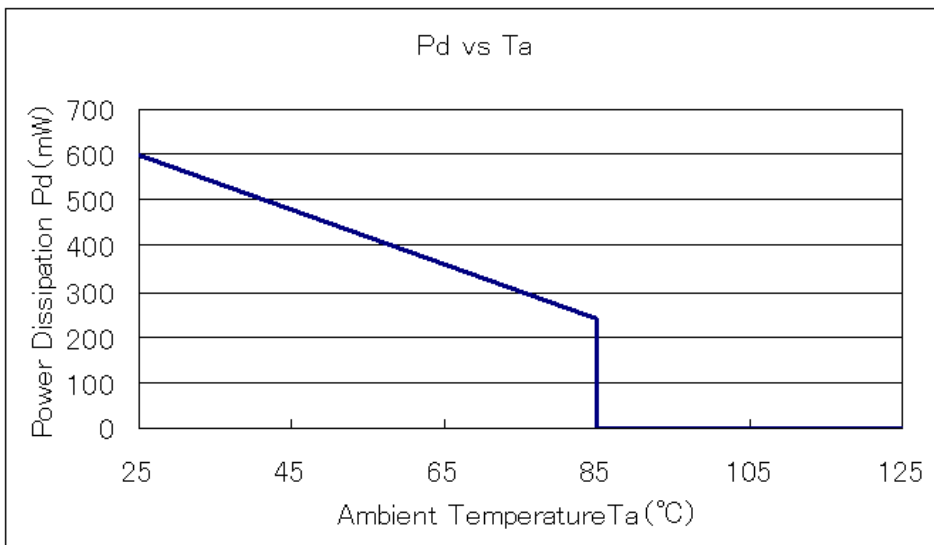


Evaluation Board (Unit: mm)

**2. Power Dissipation vs. Ambient temperature**

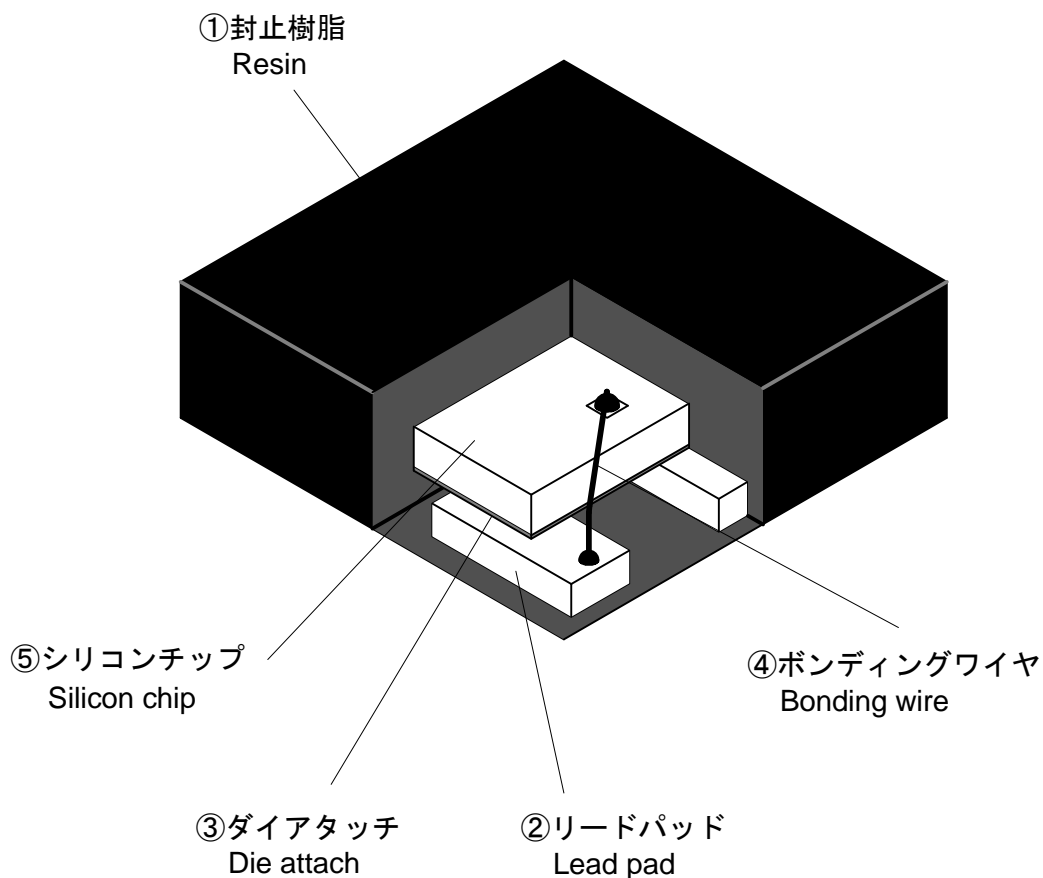
Board Mount (  $T_{jmax}=125^{\circ}C$  )

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	600	166.67
85	240	



USPN-6 構造図  
USPN-6 Perspective

RoHS対応品  
RoHS Compliance



項目 Item	材料 Material	備考 Note
① 封止樹脂 Resin	エポキシ樹脂 Epoxy resin	難燃グレード/Flammability rating UL94V-0
② リードパッド Lead pad	ニッケル Nickel	
	端子処理 Outer pad plating	Auメッキ Gold plating
③ ダイアタッチ Die attach	ダイアタッチフィルム Die attach film	
④ ボンディングワイヤ Bonding wire	Au	
⑤ シリコンチップ Silicon chip	Si	

捺印表示 Marking	レーザー Laser marking
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